

Miniature LED Driver

PRODUCTION DATA SHEET

DESCRIPTION

The Microsemi LX1995-x is a small inductor and filter capacitor.

The driver supports a wide input start up at 1.6V input. The LX1995-x (switching current is 325mA). driver. The design is based on a (switching current is 500mA). pseudo-hysteretic pulse frequency modulation topology. In portable battery applications the LX1995-x offers high system efficiency with low quiescent current: in operation I_Q is < 70μ A and in standby I₀ is < 1μ A.

The LX1995-x output current is miniature LED driver with integrated programmable using an external current drivers. It is designed to drive white sense resistor in series with LEDs. This or color LEDs in portable display configuration provides a feedback to the applications. The LX1995-x is an FB pin which maintains constant output adjustable step-up boost converter. current independent of input voltage The LX1995-x can switch up to 2MHz and LED forward voltage (VF). LED allowing designers to use a low cost, dimming is accomplished using a PWM signal or varying DC voltage methods.

The LX1995-x is available in the 5voltage range (1.6V to 5.5V) with Pin TSOT and SOT-23 package. The efficiency greater than 85% and can LX1995-1 can drive up to 6 LEDs The is a low cost, high efficiency LED LX1995-2 can drive up to 10 LEDs

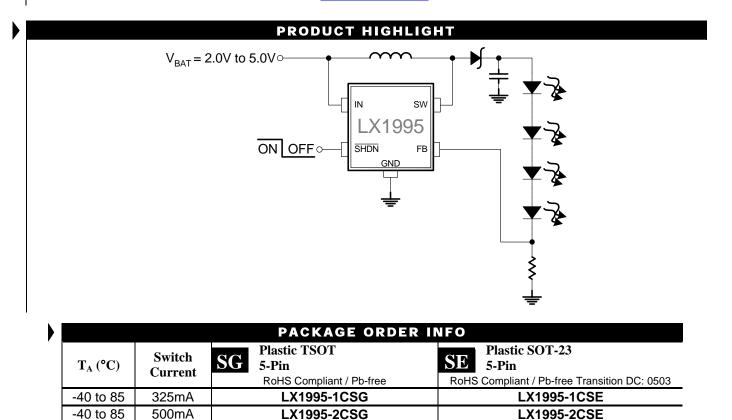
KEY FEATURES

- < 1µA Shutdown Current</p>
- > 85% Maximum Efficiency
- Efficient at Low Current Levels
- < 70µA Quiescent Supply Current in Operating Mode
- V_{IN} Range 1.6V to 5.5V
- Logic Controlled Shutdown
- Dimming Options: PWM or Varying DC Voltage
- Tiny 5-Pin TSOT Package
- Smallest External Components

APPLICATIONS

- Pagers
- Wireless Phones
- PDAs
- LED Driver
- Digital Camera Displays
 - **GPS** Receivers

IMPORTANT: For the most current data, consult MICROSEMI's website: http://www.microsemi.com



Note: Available in Tape & Reel. Append the letters "TR" to the part number. (i.e. LX1995-1CSG-TR)



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IN

SHDN

IN

SHDN

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SW

GND

FB

SW

GND

FB

PACKAGE PIN

1

2

3

1

2

3

SG PACKAGE (Top View)

5

4

SE PACKAGE

(Top View)

RoHS / Pb-free 100% Matte Tin Lead Finish

ABSOLUTE MAXIMUM RATINGS

Supply Input Voltage	
Feedback Peak Pulse Input Voltage (V _{FB})	0.3V to $V_{IN} + 0.3V$
Shutdown Input Voltage (V _{SHDN})	0.3V to $V_{IN} + 0.3V$
Switch Voltage (V _{SW})	0.3V to 30V
Switch Current (I _{SW})	500mA
Operating Temperature Range	40°C to 85°C
Maximum Operating Junction Temperature	125°C
Storage Temperature Range	65°C to 150°C
Peak Package Solder Reflow Temp. (40 second max. e	

Note: Exceeding these ratings could cause damage to the device. All voltages are with respect to Ground. Currents are positive into, negative out of specified terminal.

THERMAL DATA

SG Plastic TSOT 5-Pin

THERMAL RESISTANCE-JUNCTION TO AMBIENT, θ_{JA}

SE Plastic SOT-23 5-Pin

THERMAL RESISTANCE-JUNCTION TO AMBIENT, θ_{JA}	191°C/W
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Junction Temperature Calculation: $T_J = T_A + (P_D \ x \ \theta_{JA})$.

The θ_{JA} numbers are guidelines for the thermal performance of the device/pc-board system. All of the above assume no ambient airflow.

FUNCTIONAL PIN DESCRIPTION

207°C/W

Name	Description
SW	Inductor Switching Connection – Internally connected to the drain of a 28V N-channel MOSFET. SW is high impedance in shutdown.
GND	Common terminal for ground reference.
FB	Feedback Input – Connect to a current sense resistor between the load and GND to set the maximum output current. FB pin is regulated to 320mV.
SHDN	Active-Low Shutdown Input – A logic low shuts down the device and reduces the supply current to <1 μ A. Connect SHDN to V _{CC} for normal operation.
IN	Unregulated IC Supply Voltage Input – Input range from +2.0V to +5.5V. Bypass with a 1μ F or greater capacitor for low voltage operation.



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ELECTRICAL CHARACTERISTICS

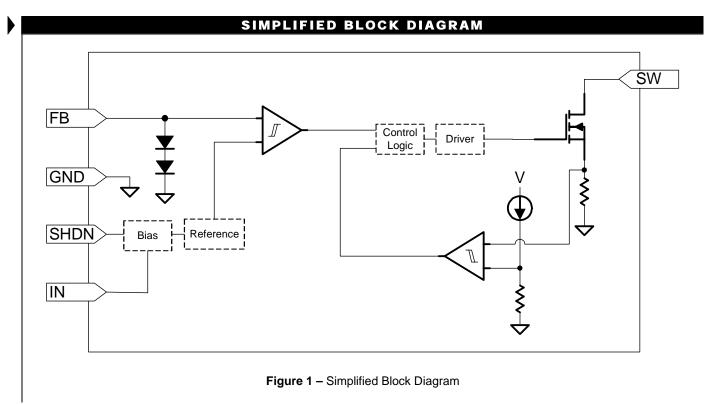
Unless otherwise specified, the following specifications apply over the operating ambient¹ temperature $0^{\circ}C \le T_A \le 70^{\circ}C$ except where otherwise noted and the following test conditions: $V_{IN} = 3V$, $V_{\overline{SHDN}} = V_{IN}$. Unless where indicated, these parameters apply to both the LX1995-1 and LX1995-2 part versions.

Parameter	Symbol	Test Conditions	L	LX1995-x		
Faiailletei	Symbol		Min	Тур	Max	Units
Operating Voltage	V _{IN}		1.6		5.5	V
Minimum Start-up Voltage	V _{SU}	$T_A = +25^{\circ}C$			1.6	V
Start-up Voltage Temperature Coefficient	k _{VST}	Guaranteed; not tested		-2		mV/°C
Quiescent Current	, N	Not switching		70	100	μΑ
	IQ	$V_{\overline{SHDN}} < 0.4V$		0.2	0.5	
FB Threshold Voltage	V _{FB(TH)}		288	320	352	mV
FB Input Bias Current	I _{FB}	Not Switching, $V_{FB} = 400 \text{mV}$	-10		10	nA
Shutdown Input Bias Current		$V_{\overline{SHDN}} = 0V$	-100		100	nA
Shutdown Low Input Voltage	V _{SHDN}				0.6	V
Shutdown High Input Voltage			1.4			v
Switch Peak Current	IPEAK	L= 47μH; LX1995-1	250	325	400	mA
Switch Peak Current	IPEAK	L= 47μH; LX1995-2	400	500	600	mA
Minimum Switch Off-Time	t _{OFF}	$T_{A} = +25^{\circ}C; V_{FB} < V_{FB(TH)}$		300		ns
Switch Pin Leakage Current	ILEAK	$V_{SW} = 28V$		0.23		μΑ

Note:

1. Low duty cycle pulse testing techniques are used which maintains junction and case temperatures equal to the ambient temperature.

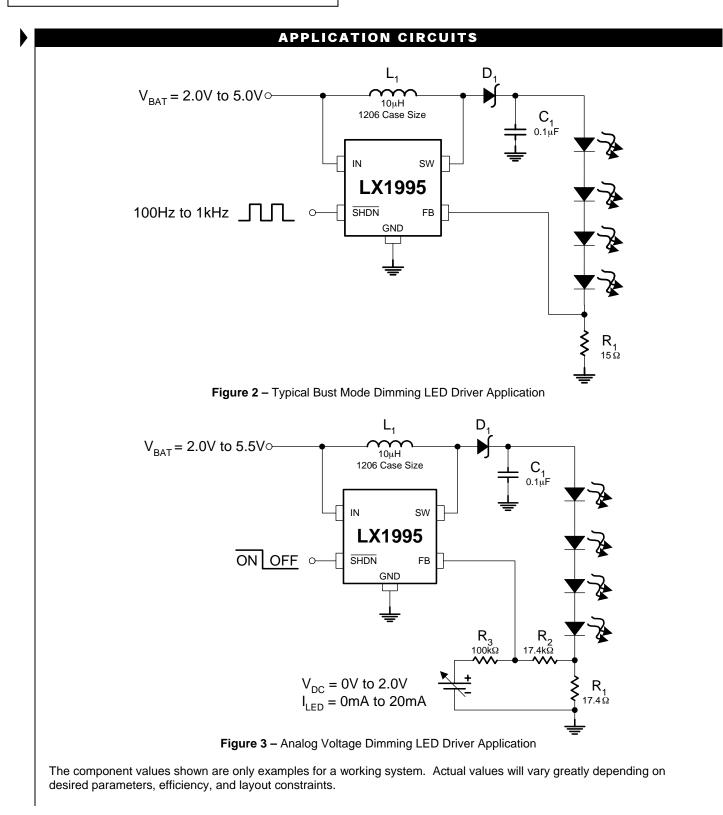
2. Functionality over the -40°C to +85°C operating temperature range is assured by design, characterization, and correlation.





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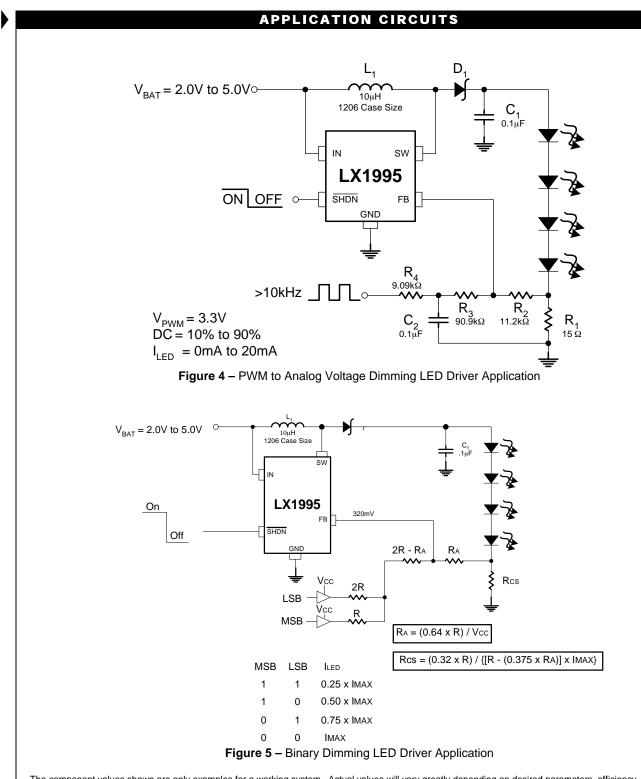
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The component values shown are only examples for a working system. Actual values will vary greatly depending on desired parameters, efficiency, and layout constraints.

Microsemi_®

LX1995

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THEORY OF OPERATION

OPERATING THEORY

The LX1995-x is a PFM boost converter optimized for driving a series of white or color LEDs. It operates in a pseudo-hysteretic mode with a fixed, 300ns, switch "off time". When the LX1995-x enables, the LED current decreases causing the FB voltage to decrease to a value less than 320mV. The feedback comparator (See Simplified Block Diagram) activates the control logic. The control logic turns on the DRV output circuit that connects to the internal N-Channel MOSFET gate. The switch output (SW) is switched "on" and remains "on" until the inductor current ramps up to the peak current level (typically 325mA for LX1995-1).

The LED load is powered from energy stored in the output capacitor during the inductor charging cycle. Once the peak inductor current value is achieved, the output is turned off and the energy stored in the inductor delivers to the load. This causes the voltage to rise across the current setting resistor (R₁) at the input to the feedback circuit. The LX1995-x continues to switch until the voltage at the FB pin exceeds 320mV. The value of R₁ is calculated by dividing 320mV by the maximum series LED current. A minimum value of 3.3 Ω is recommended for R_{SET}. The voltage at the FB pin is the product of the LED current (I_{LED}) and R₁.

$$R_1 = \frac{320 \text{mV}}{\text{I}_{\text{LED(MAX)}}} \qquad \text{eq. 1}$$

DIMMING METHODS

LX1995-x supports two dimming methods: PWM or DC Voltage.

PWM mode: Connect system PWM logic signal to the SHDN pin (See Figure 1). This turns the LX1995-X on and off which pulses the LED current between zero and the setting determined by R_1 .

DC Voltage mode: The designer can apply an adjustable DC voltage supply to the FB pin. As the DC voltage increases, the LED current decreases. The equation (see Figure 3) is:

$$I_{\text{LED}} = \frac{1}{R_1} \left[320 \text{mV} \cdot \left(\frac{R_2 + R_3}{R_3} \right) - V_{\text{ADJ}} \cdot \left(\frac{R_2}{R_3} \right) \right] \qquad \text{eq. 2}$$

INDUCTOR SELECTION AND OUTPUT CURRENT LIMIT PROGRAMMING

Microsemi recommends the use inductors (for the LX1995-1) in the range of 10μ H to 47μ H due to saturation of peak inductor current. By increasing the average inductor current, the LX1995-x will extend the power range. Smaller inductor values will reduce output voltage ripple and are smaller in size.

OUTPUT RIPPLE AND CAPACITOR SELECTION

Output voltage ripple is depended on the selection of the inductor value (L), output capacitor value (C_{OUT}), peak switch current (I_{PEAK}), load current (I_{OUT}), input voltage (V_{IN}) and the output voltage (V_{OUT}). The peak-to-peak voltage ripple is a function of the output droop (as the inductor current charges to I_{PEAK}), the feedback transition error (i.e., typically 10mV), and the output overshoot (energy stored in the inductor). When the switch is first turn on, the total ripple voltage is:

$$V_{\text{RIPPLE}} = \Delta V_{\text{DROOP}} + \Delta V_{\text{OVERSHOOT}} + 10 \text{mV}$$
 eq. 3

The initial droop can be estimated with the assumption of 0.5V of voltage drop across the inductor and FET RDS_{ON}.

$$\Delta V_{\text{DROOP}} = \frac{\left(\frac{L}{C_{\text{OUT}}}\right) \cdot \left(I_{\text{PK}} \times I_{\text{LED}}\right)}{V_{\text{IN}} - 0.5} \qquad \text{eq. 4}$$

The output overshoot calculated with 0.5V as voltage drop across the diode.

$$\Delta V_{\text{OVERSHOOT}} = \frac{\frac{1}{2} \cdot \left(\frac{L}{C_{\text{OUT}}}\right) \cdot \left(I_{\text{PK}} - I_{\text{LED}}\right)^2}{V_{\text{OUT}} - V_{\text{IN}} + 0.5} \qquad \text{eq. 5}$$

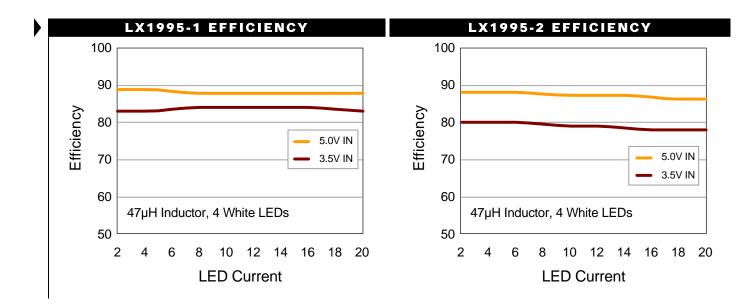
Once the output voltage ripple is determined for the selected components, the output capacitor can then be adjusted to meet the target ripple voltage requirements.

The LX1995-x is targeted for LED driver applications; output voltage ripple is not a critical application requirement.



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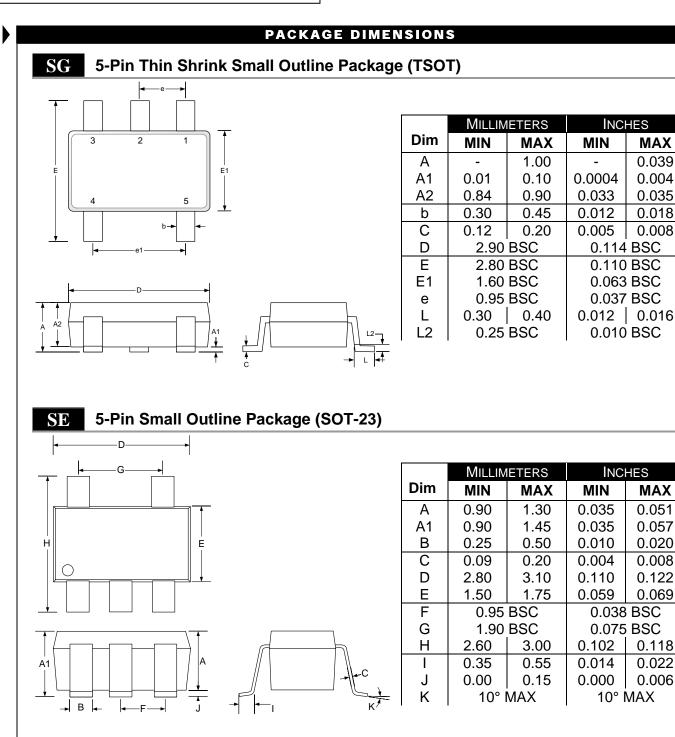
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Note: Dimensions do not include mold flash or protrusions; these shall not exceed 0.155mm(.006") on any side. Lead dimension shall not include solder coverage.



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NOTES

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